CHIPQUIK® TC1-10G

Datasheet revision 1.8 www.chipquik.com

Heat Sink Compound - High Density 10g Syringe 5cc

Product Highlights

- High Density Thermal Paste.
- White, non-curing and non-flowing thermally conductive heat sink compound.
- Heavily filled with heat-conductive metal oxide. Provides high thermal conductivity, low bleed and high temperature stability.
- Electrically insulating (2 x 10^{15} ohm-cm).

Specifications

Viscosity:	542,000 cP (542,000 mPa·s)
Density:	2.1g/cc
Bleed:	0.23%
Thermal Conductivity:	0.67 W/m·K*
Thermal Resistance:	0.16 °C*cm^2/W
Electrical Volume Resistivity:	2 x 10^{15} ohm-cm
Dielectric Strength:	8.27 MV/m (210V/mil)
Evaporation:	0.38%
Operating Temperature (Continuous):	-40 to 150°C (-40 to 302°F)
Operating Temperature (Peak):	200°C (392°F)
Operating Life:	>8 years *dependent on several factors, test in application to ensure suitability
Size:	10g Syringe (5cc)

Storage and Handling

Store refrigerated or at room temperature 3-25°C (37-77°F). Allow 4 hours for thermal paste to reach an application temperature of 20-25°C (68-77°F) before use.

Shelf Life

>60 months

Stencil Life

>7 days @ 20-70% RH 22-28°C (72-82°F)

Transportation

This product has no shipping restrictions. Shipping below 0°C (32°F) or above 25°C (77°F) for normal transit times by ground or air will not impact this product's stated shelf life.

* Calculated based on industry data and measurements from testing in the Chip Quik laboratory, using proprietary modified hot plate test method, using 12.7mm (0.5") diameter copper substrates, with thermal interface material (TIM) applied between substrates in a fine layer.
Thermal conductivity of TIMs is highly dependent on application, quantity used, pressure, substrate material and any coatings applied. Testing in end use application is required to determine actual thermal conductivity achieved in application, as it may be higher or lower, dependent on a large number of application specific factors.

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Chip Quik® Thermal Paste Orderable Part Numbers

Thermal Conductivity (W/m·K)	Thermal Resistance (°C*cm^2/W)	Density (g/cc)	Color	Package	Size (g)	Orderable Part Number
0.67	0.16	2.1	White	Syringe	10	TC1-10G
0.67	0.16	2.1	White	Syringe	20	TC1-20G
0.67	0.16	2.1	White	Jar	200	TC1-200G
4.3	0.06	2.5	Grey	Syringe	10	TC2-10G
4.3	0.06	2.5	Grey	Syringe	20	TC2-20G
4.3	0.06	2.5	Grey	Jar	50	TC2-50G
8.5	0.03	2.5	Grey	Syringe	1	TC3-1G
8.5	0.03	2.5	Grey	Syringe	3.5	TC3-3.5G
8.5	0.03	2.5	Grey	Syringe	10	TC3-10G

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